


INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)				ATTY. DOCKET NO. 007734 FPS/MMCS/APC		SERIAL NO. 10/665,165	
				APPLICANT Joseph Young J. PAIK			
				FILING DATE September 18, 2003		GROUP	
U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
	4,957,605	09/18/90	Hurwitt et al.			04/17/89	
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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
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	3,767,900	10/23/73	Chao et al.			06/23/71	
	3,920,965	11/18/75	Sohrwardy			03/04/74	
	4,000,458	12/28/76	Miller et al.			08/21/75	
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	4,302,721	11/24/81	Urbanek et al.			05/15/79	
	4,368,510	01/11/83	Anderson			10/20/80	
	4,609,870	09/02/86	Lale et al.			09/13/84	
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	5,926,690	07/20/99	Toprac et al.			05/28/97	
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	6,017,771	01/25/00	Yang et al.			04/27/98	
	6,036,349	03/14/00	Gombar			07/26/96	
	6,041,263	03/21/00	Boston et al.			10/01/97	
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U.S. PATENT DOCUMENTS						
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	6,127,263	10/03/00	Parikh			07/10/98
	6,128,016	10/03/00	Coelho et al.			12/20/96
	6,136,163	10/24/00	Cheung et al.			03/05/99
	6,141,660	10/31/00	Bach et al.			07/16/98
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EXAMINER'S INITIALS	PATENT APP. NO.	FILING DATE	NAME	TITLE	CLASS	SUB- CLASS	
	09/363,966	07/29/99	Arackaparambil et al.	Computer Integrated Manufacturing Techniques			
	09/469,227	12/22/99	Somekh et al.	Multi-Tool Control System, Method and Medium			
	09/619,044	07/19/00	Yuan	System and Method of Exporting or Importing Object Data in a Manufacturing Execution System			
	09/637,620	08/11/00	Chi et al.	Generic Interface Builder			
	09/656,031	09/06/00	Chi et al.	Dispatching Component for Associating Manufacturing Facility Service Requestors with Service Providers			
	09/655,542	09/06/00	Yuan	System, Method and Medium for Defining Palettes to Transform an Application Program Interface for a Service			
	09/725,908	11/30/00	Chi et al.	Dynamic Subject Information Generation in Message Services of Distributed Object Systems			
	09/800,980	03/08/01	Hawkins et al.	Dynamic and Extensible Task Guide			
	09/811,667	03/20/01	Yuan et al.	Fault Tolerant and Automated Computer Software Workflow			
	09/927,444	08/13/01	Ward et al.	Dynamic Control of Wafer Processing Paths in Semiconductor Manufacturing Processes			
	09/928,473	08/14/01	Koh	Tool Services Layer for Providing Tool Service Functions in Conjunction with Tool Functions			
	09/928,474	08/14/01	Krishnamurthy et al.	Experiment Management System, Method and Medium			
	09/943,383	08/31/01	Shanmugasundram et al.	In Situ Sensor Based Control of Semiconductor Processing Procedure			
	09/943,955	08/31/01	Shanmugasundram et al.	Feedback Control of a Chemical Mechanical Polishing Device Providing Manipulation of Removal Rate Profiles			
	09/998,372	11/30/01	Paik	Control of Chemical Mechanical Polishing Pad Conditioner Directional Velocity to Improve Pad Life			
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	10/100,184	03/19/02	Al-Bayati et al.	Method, System and Medium for Controlling Semiconductor Wafer Processes Using Critical Dimension Measurements			
	10/135,405	05/01/02	Reiss et al.	Integration of Fault Detection with Run-to-Run Control			
	10/135,451	05/01/02	Shanmugasundram et al.	Dynamic Metrology Schemes and Sampling Schemes for Advanced Process Control in Semiconductor Processing			
	10/172,977	06/18/02	Shanmugasundram et al.	Method, System and Medium for Process Control for the Matching of Tools, Chambers and/or Other Semiconductor-Related Entities			
	10/173,108	06/18/02	Shanmugasundram et al.	Integrating Tool, Module, and Fab Level Control			
	10/174,370	06/18/02	Shanmugasundram et al.	Feedback Control of Plasma-Enhanced Chemical Vapor Deposition Processes			
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	10/377,654	03/04/03	Kokotov et al.	Method, System and Medium for Controlling Manufacturing Process Using Adaptive Models Based on Empirical Data			
	10/393,531	03/21/03	Shanmugasundram et al.	Copper Wiring Module Control			
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						Yes	No
	61-66104	04/04/86	Japan			X	
	61-171147	08/01/86	Japan			X	
	01-283934	11/15/89	Japan			X	
	0 397 924 A1	11/22/90	Europe			X	
	2,050,247	08/29/91	Canada			X	
	2,165,847	08/29/91	Canada			X	
	2,194,855	08/29/91	Canada			X	
	3-202710	09/04/91	Japan			X	
	05-151231	06/18/93	Japan			X	
	05-216896	08/27/93	Japan			X	
	05-266029	10/15/93	Japan			X	
	06-110894	04/22/94	Japan			X	
	06-176994	06/24/94	Japan			X	
	06-184434	07/05/94	Japan			X	
	06-252236	09/09/94	Japan			X	
	06-260380	09/16/94	Japan			X	
	EP 0 621 522 A2	10/26/94	Europe			X	
	WO 95/34866	12/21/95	WO			X	
	8-23166	01/23/96	Japan			X	
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	08-149583	06/07/96	Japan			X	
	08-304023	11/22/96	Japan			X	
	EP 0 747 795 A2	12/11/96	Europe			X	
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	9-246547	09/19/97	Japan			X	
	WO 98/05066	02/05/98	WO			X	
	10-34522	02/10/98	Japan			X	
	10-173029	06/26/98	Japan			X	
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	EP 0 869 652 A2	10/07/98	Europe			X	
	WO 98/45090	10/15/98	WO			X	
	EP 0 877 308 A2	11/11/98	Europe			X	
	EP 0 881 040 A2	12/02/98	Europe			X	
	EP 0 895 145 A1	02/03/99	Europe			X	
	WO 99/09371	02/25/99	WO			X	
	11-67853	03/09/99	Japan			X	
	EP 0 910 123 A1	04/21/99	Europe			X	
	11-126816	05/11/99	Japan			X	
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	WO 99/25520	05/27/99	WO			X	
	EP 0 932 194 A1	07/28/99	Europe			X	
	WO 99/59200	11/18/99	WO			X	
	WO 00/00874	01/06/00	WO			X	
	WO 00/05759	02/03/00	WO			X	
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	GB 2 347 885 A	09/20/00	United Kingdom			X	
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	WO 01/25865 A1	04/12/01	WO			X	
	EP 1 092 505 A2	04/18/01	Europe			X	
	WO 01/33277 A1	05/10/01	WO			X	
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	434103	05/16/01	Taiwan			X	
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	WO 01/52055 A3	07/19/01	WO			X	
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	APPLICANT Joseph Young J. PAIK	
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